

## PATENT ABSTRACTS OF JAPAN

(11) Publication number : 09-107046  
 (43) Date of publication of application : 22.04.1997

(61) Int.CI.

H01L 23/12

(21) Application number : 07-262818  
 (22) Date of filing : 11.10.1995

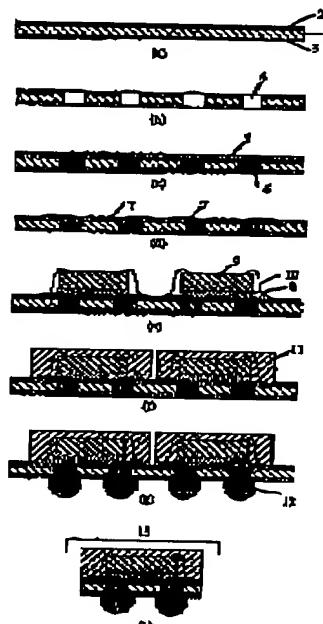
(71) Applicant : HITACHI CHEM CO LTD  
 (72) Inventor : TSUBOMATSU YOSHIAKI  
 INOUE FUMIO  
 YAMAZAKI AKIO  
 OHATA HIROTO  
 ICHIMURA SHIGEKI  
 TAGUCHI NORIYUKI

## (54) SEMICONDUCTOR PACKAGE

## (57) Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor package adaptable for reducing the size and increasing the density of the package.

SOLUTION: A semiconductor package has a board for mounting a semiconductor chip 9 on an insulation board, interconnection pattern 7 electrically connected to semiconductor chip electrodes formed on one side of the board, external connection terminals 12 formed on the other side of the board 1, and layer interconnection 6 connecting the pattern 7 to the terminals 12. The substrate is formed so that the end part of the pattern connected to the interconnection 6 may be within a plane region exposed of the interconnection 6.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C) 1998, 2000 Japanese Patent Office